## SHARP

Spec No.	DG-129002
Issue	04-Sep-12

# S P E C I F I C A T I O N S

Product Type

## ZENIGATA LED

Model No.

## GW6BME\*\*HED

## \*\*: 27, 30, 40, 50

These specifications contain <u>17</u> pages including the cover and appendix. If you have any objections, please contact us before issuing purchasing order.

CUSTOMERS ACCEPTANCE

DATE:

BY:

Reference

PRESENTED

BY: T. Uemura Dept. General Manager

REVIEWED BY:

PREPARED BY:

Development Department II Lighting Device Division Electronic Components And Devices Group SHARP CORPORATION

### Model No. **GW6BME\*\*HED**



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• When using the products covered herein, please observe the conditions written herein and the precautions outlined in the following paragraphs. In no event shall the company be liable for any damages resulting form failure to strictly adhere to these conditions and precautions.

(1) Please do verify the validity of this part after assembling it in customer's products, when customer wants to make catalogue and instruction manual based on the specification sheet of this part.

(2) The products covered herein are designed and manufactured for the following application areas. When using the products covered herein for the equipment listed in paragraph (3), even for the following application areas, be sure to observe the precautions given in Paragraph (3). Never use the products for the equipment listed in Paragraph (4).

- $\cdot$  Office electronics
- ·Instrumentation and measuring equipment
- Machine tools
- Audiovisual equipment
- Home appliances
- ·Communication equipment other than for trunk lines
- (3) These contemplating using the products covered herein for the following

equipment which demands high reliability, should first contact a sales representative of the company and then accept responsibility for incorporating into the design fail-safe operation, redundancy, and other appropriate measures for ensuring reliability and safety of the equipment and the overall system.

·Control and safety devices for airplanes, trains, automobiles, and other

- transportation equipment
- · Mainframe computers
- ·traffic control systems
- ·Gas leak detectors and automatic cutoff devices
- ·Rescue and security equipment
- ·Other safety devices and safety equipment, etc.

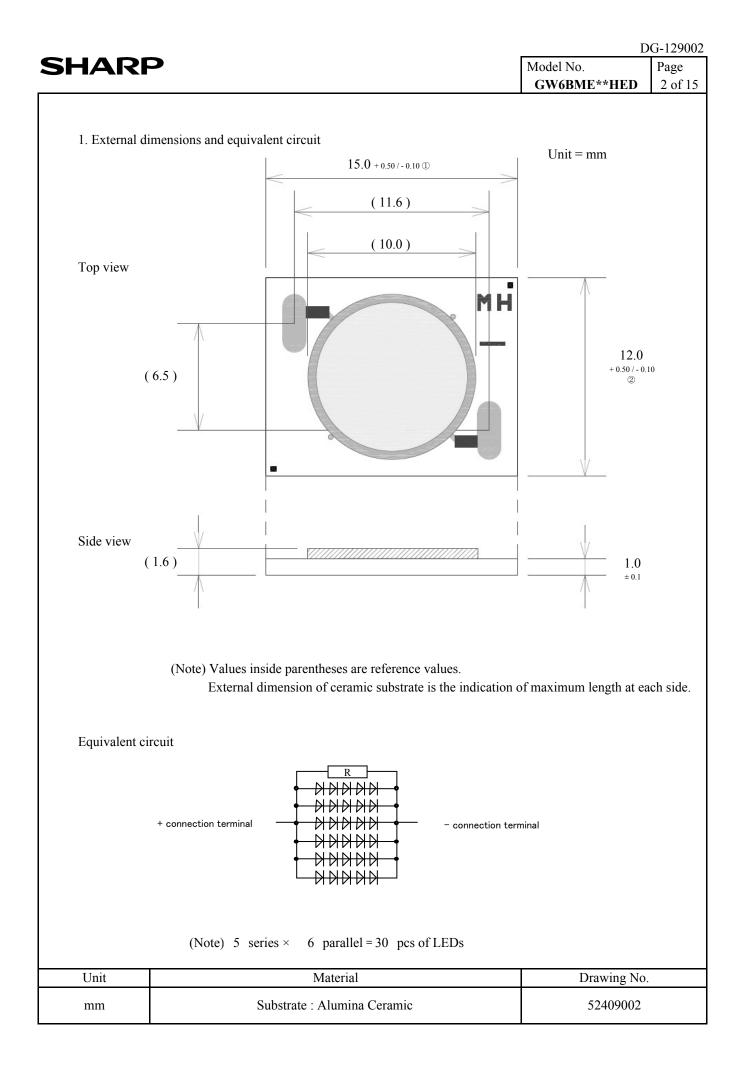
(4) Do not use the products covered herein for the following equipment which

demands extremely high performance in terms of functionality, reliability, or accuracy.

- ·Aerospace equipment
- ·Communications equipment for trunk lines
- ·Control equipment for the nuclear power industry
- ·Medical equipment related to life support, etc.
- (5) please direct all queries and comments regarding the interpretation of the above four Paragraphs to a sales representative of the company.

 Please direct all queries regarding the products covered herein to a sales representative of the company.

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		GWUDHIE HED	10
GW6BME**HED specification	15		
<ol> <li>Application         These specifications apply to the light emitting diode module Mode             [ LED module (InGaN Blue LED chip + Phosphor) ]             Main application : Lighting         </li> </ol>	el No. GW6	BME**HED.	
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3. Ratings and characteristics

3-1. Absolute maximum ratings

Item	Symbol	Rating	Unit
Power Dissipation *1,4	Р	12.8	W
Forward Current *1,4	I <sub>F</sub>	780	mA
Reverse Voltage *2,4	V <sub>R</sub>	-15	V
Operating Temperature *3	T <sub>opr</sub>	- 30 ∼ + 100	°C
Storage Temperature	T <sub>stg</sub>	- 40 ~ + 100	°C

\*1 Power dissipation and forward current are the value when the module temperature is set lower than the rating by using an adequate heat sink.

\*2 Voltage resistible at initial connection error

(Not dealing with the possibility of always-on reverse voltage.)

\*3 Case temperature Tc (Refer to measuring point for case temperature in the next page.) Refer to "Derating curve" in the next page as for operating current.

\*4 T<sub>c</sub> = 25  $^{\circ}$ C

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#### 3-2. Electro-optical characteristics

	tro optical characteristics					(T <sub>j</sub>	= 90 °C
**	Item	Symbol	Condition	MIN.	TYP.	MAX.	Unit
common	Forward Voltage *5	V <sub>F</sub>	$I_F = 480 \text{ mA}$	13.2	(15.0)	16.5	V
	Luminous Flux *6	Φ		540	(620)	-	lm
	Chromaticity Coordinates *7	X		-	(0.4610)	-	-
27	Chromatienty Coordinates • 7	у	$I_F = 480 \text{ mA}$	-	(0.4150)	-	-
	Color Temperature	-		-	(2700)	-	Κ
	General Color Rendering Index *8	Ra		80	(83)	-	-
	Luminous Flux *6	Φ		570	(650)	-	lm
	Chromaticity Coordinates *7	x		-	(0.4370)	-	-
30	Chromatienty Coordinates • 7	у	$I_F = 480 \text{ mA}$	-	(0.4030)	-	-
	Color Temperature	-		-	(3000)	-	Κ
	General Color Rendering Index *8	Ra		80	(83)	-	-
	Luminous Flux *6	Φ		620	(700)	-	lm
	Chromaticity Coordinates *7	x		-	(0.3820)	-	-
40	Chromatienty Coordinates • 7	у	$I_F = 480 \text{ mA}$	-	(0.3800)	-	-
	Color Temperature	-		-	(4000)	-	Κ
	General Color Rendering Index *8	Ra		80	(82)	-	-
	Luminous Flux *6	Φ		640	(720)	-	lm
	Chromaticity Coordinates *7	X		-	(0.3480)	-	-
50	Chromaticity Coordinates */	у	$I_F = 480 \text{ mA}$	-	(0.3600)	-	-
	Color Temperature	-	]	-	(5000)	-	K
	General Color Rendering Index *8	Ra		80	(82)	-	-

(Note) Values inside parentheses are shown for reference purpose only.

- \*5 (After 20 ms drive, Measurement tolerance:  $\pm 3$  %)
- \*6 Monitored by Sharp's 8 inch integrating sphere and Otsuka electronics MCPD-LE3400 (After 20 ms drive, Measurement tolerance: ± 10 %)
- \*7 Monitored by Sharp's 8 inch integrating sphere and Otsuka electronics MCPD-LE3400 (After 20 ms drive, Measurement tolerance: ± 0.005)
- \*8 Monitored by Sharp's 8 inch integrating sphere and Otsuka electronics MCPD-LE3400 (After 20 ms drive, Measurement tolerance: ± 2)

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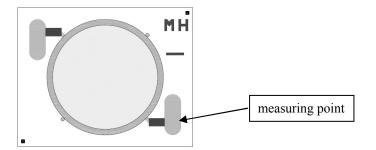
ARF		Model No. GW6BME**HED	DG-12 Pag 5 o
3. Derating	curve		
	Forward Current Derating Curve		
900 800			
Current I <sub>F</sub> [mA] 200 700 700 700 700 700 700 700 700 700			
und Gut I 100 € Eut I 100 € Eut I			
a 300			
200 Long 100	$\begin{array}{ c c c c c c c c c c c c c c c c c c c$		
0			
-3	30     -20     -10     0     10     20     30     40     50     60     70     80	90 100 110	

(Note) To keep the case temperature lower than the rating, enough heat-radiation performance needs to be secured by using an adequate heat sink.

For soldering connection, please evaluate in your circumstance to make sure soldering reliability. (Above derating curve is specified to LED device, not for soldering connection) And please consider to avoid physical stress between wire and substrate, and some protection like silicon bond on top of soldered wire is recommended.

Please ensure the maintenance of heat radiation not to exceed case temperature over the rating in operation.

(Measuring point for case temperature)



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### 4. Reliability

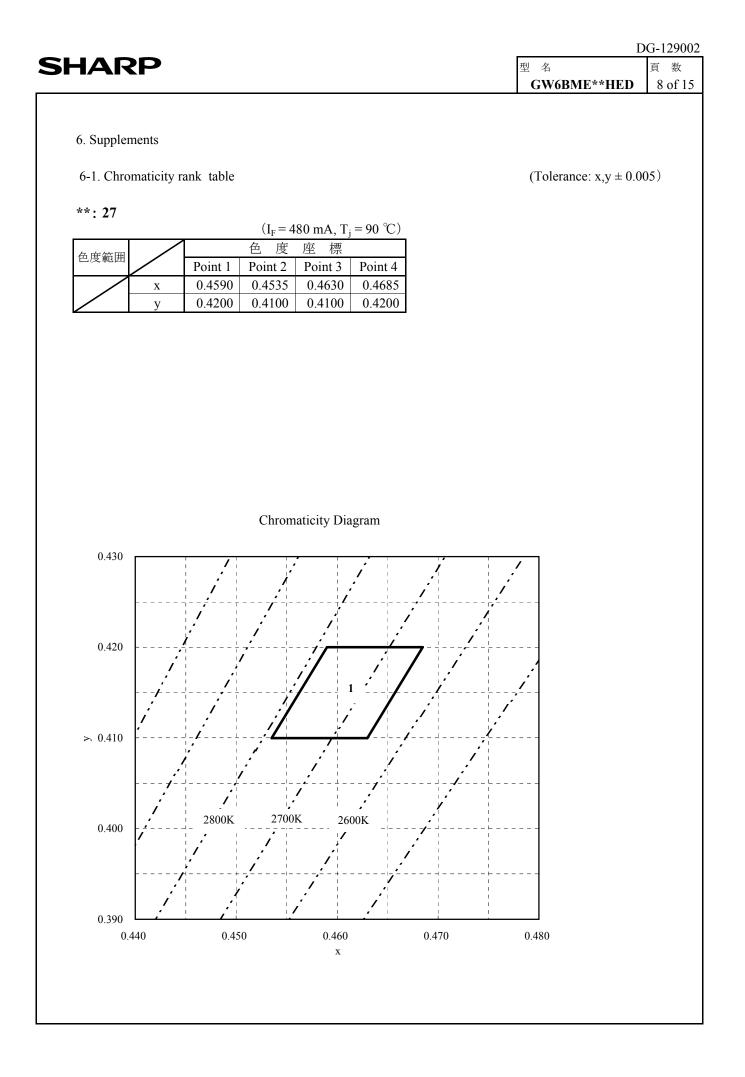
The reliability of products shall be satisfied with items listed below.

4-1.7	Test items and test condit	ions	Co	nfidence le	vel: 90 %
No.	Test item	Test conditions	Samples	Defective	LTPD
			n	С	(%)
1	Temperature Cycle	- 40 °C(30 min) $\sim$ + 100 °C(30 min), 100 cycles			
			11	0	20
2	Temperature Humidity	$T_{stg} = +60 ^{\circ}\text{C}, \text{RH} = 90 ^{\circ}\text{M}, \text{Time} = 1000 \text{ h}$			
	Storage		11	0	20
3	High Temperature	$T_{stg} = +100$ °C, Time = 1000 h			
	Storage		11	0	20
4	Low Temperature	$T_{stg} = -40 \text{ °C}, \text{ Time} = 1000 \text{ h}$			
	Storage		11	0	20
5	Steady State Operating	$T_c = 60 \ ^{\circ}C$ , $I_F = 780 \ mA$ , Time = 1000 h			
	Life		11	0	20
6	Shock	Acceleration: 15000 m/s <sup>2</sup> , Pulse width: 0.5 ms			
		Direction: 3 directions (X, Y and Z)			
		3 trials in each direction	5	0	50
7	Vibration	Frequency: 100 to 2000 Hz for 4 minutes per trial			
		Acceleration: 200 m/s <sup>2</sup>			
		Direction: 3 directions (X, Y and Z)			
		4 trials in each direction	5	0	50

### 4-2. Failure criteria

	411410 01100114		
No.	Parameter	Symbol	Failure criteria
1	Forward Voltage	V <sub>F</sub>	$V_F > Initial value \times 1.1$
2	Luminous Flux	Φ	$\Phi \le$ Initial value $\times 0.7$

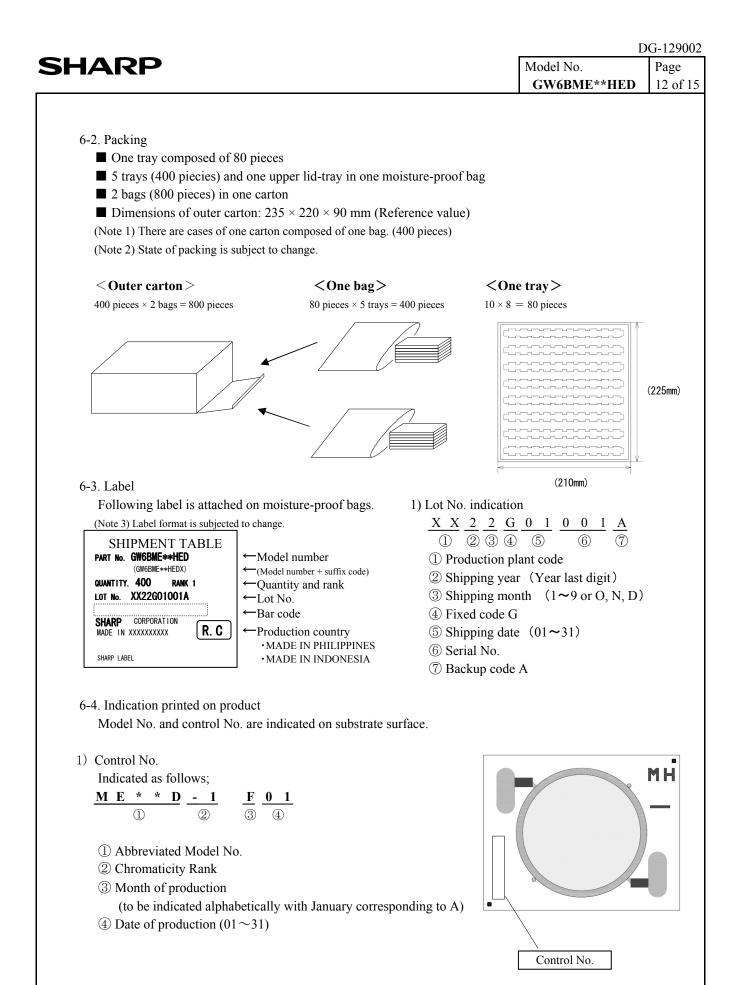
	RP		Model No. GW6BM			G-1290 Page 7 of 1
5. Qu	ality level					
	Applied standard SO2859-1					
A 5-3.1	Inspection items a	mpling plan, level S-4.				
	Item	Defect criteria	<b>a</b> 1	ification	AQL	
No.	Item	Delect chiefia	Classi	Incation	AQL	/
<u>No.</u> 1	No radiation	No light emitting	M	ajor fect	0.1	,
	No radiation Electro-optical	No light emitting Not conforming to the specification	M	ajor		,
1	No radiation	No light emitting	M	ajor		<u>,                                     </u>



					刑友	D	G-1290
IARP					型 名 GW6BMI	E**HED	頁 数 9 of 1
					(Tolerance	$x,y \pm 0.00$	05)
**: 30							
		= 480 mA, T <sub>j</sub> = 90 度 座 標	°C)				
色度範囲 X	Point 1         Point 1           0.4350         0.429	2 Point 3 Point	nt 4 445				
y y	0.4080 0.398		080				
	Chr	romaticity Diagran	n				
0.420		; ;	:				
			1				
		_ <u>_</u>		;			
0.410	 						
0.410				;;	 / /		
0.410					 		
					 , , , , , , , , , , , , , , , , ,		
0.410 > 0.400					 		
					 ,		
	3100K				 		
> 0.400	3100K				 		
> 0.400	3100K						
> 0.400	0.425		0.44		0.455		

IARP			型 名 GW6BME**]	頁 HED 10
			GWODME	
			(Tolerance: x,	$y \pm 0.005)$
**: 40	$(1 - 480 - 100 \circ C)$			
	(I <sub>F</sub> =480 mA, T <sub>j</sub> =90 ℃) 色 度 座 標			
色度範囲	Point 1 Point 2 Point 3 Point 4			
х	0.3800 0.3745 0.3840 0.3895			
y y	0.3850 0.3750 0.3750 0.3850			
5				
	Chromaticity Diagram			
	Chromaticity Diagram			
0.400	Chromaticity Diagram			
0.400	Chromaticity Diagram			
0.400	Chromaticity Diagram			
0.400				
	Chromaticity Diagram			
0.400				
		7		
	Chromaticity Diagram	7.		
0.390	Chromaticity Diagram	7		
	Chromaticity Diagram	7		
0.390	Chromaticity Diagram	7		
0.390	Chromaticity Diagram	7.		
0.390 → 0.380		7.		
0.390	1 3800K 3900K	7.		
0.390 → 0.380	1 3800K 4000K	7.		
0.390 → 0.380	1 3800K 3900K	7.		
0.390 → 0.380	1 3800K 4000K	7.		
0.390 0.390 0.380 0.370	1 3800K 4000K	7.		
0.390 	1 3800K 4000K 4100K	7:		
0.390 0.390 0.380 0.370	0.370 0.380	7.	0.400	
0.390 	1 3800K 4000K 4100K	7:	0.400	

		DG-12900
IARP		型 名 頁 数 <b>GW6BME**HED</b> 11 of 13
**: 50	(I <sub>F</sub> = 480 mA, T <sub>j</sub> = 90 ℃) 色度座標	(Tolerance: x,y ± 0.005)
色度範囲	Point 1 Point 2 Point 3 Point 4	
1 <u>x</u> y	0.34600.34050.35000.35550.36500.35500.35500.3650	
	Chromaticity Diagram	
0.380	Chromaticity Diagram	
0.380		·
0.370		
0.370 > 0.360		0.365



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	GW6BME**HED	Pag 13 c
7. Precautions		
① Storage conditions		
Please follow the conditions below.		
• Before opened: Temperature $5 \sim 30 ^{\circ}\text{C}$ , Relative humidity less the formula of the second s	nan 60 %.	
(Before opened LED should be used within a year) $1.5 \times 10^{-10}$ C = $20^{\circ}$ C = $1.5 \times 10^{-10}$ C = $1.5 \times 10^{-10}$		
• After opened: Temperature 5 $\sim$ 30 °C, Relative humidity less that (Places apply addening within 1 work)	in 60 %.	
(Please apply soldering within 1 week) • After opened LED should be kept in an aluminum moisture proof b	ag with a maisture	
absorbent material (silica gel).	bag with a moisture	
Avoid exposing to air with corrosive gas.		
If exposed, electrode surface would be damaged, which may affect	soldering.	
	<u> </u>	
2 Usage conditions	1141	
This product is not designed for the use under any of the following Please confirm performance and reliability well enough if you use u		<b></b>
•In a place with a lot of moisture, dew condensation, briny air, and d		ons,
$(Cl, H_2S, NH_3, SO_2, NO_{X}, etc.)$	contosive gas.	
•Under the direct sunlight, outdoor exposure, and in a dusty place.		
• In water, oil, medical fluid, and organic solvent.	- <u>11 : </u>	
•Please do not use component parts contain sulfur (gasket packing,	adnesive material, etc.).	
③ Heat radiation		-
If forward current $(I_F)$ is applied to single-state module at any curre	nt, there is a risk of damaging LE.	D
or emitting smoke.		
Equip with specified heat radiator, and avoid heat stuffed inside the	module.	
(4) Installation		
Material of board is alumina ceramic. If installed inappropriately, tro	_	ue to
board crack or overheat. Please take particular notice for installation Refer to the following cautions on installation.		
Apply thermolysis adhesive, adhesive sheet or peculiar connecto	r when mounted on heat radiator	
In case of applying adhesive or adhesive sheet only, check the ef		fixing
If LED comes off from heat radiator, unusual temperature rise er	-	-
device deterioration, coming off of solder at leads, and emitting	-	0
• When LED device is mechanically fixed or locked, Please take is		ethod of
attachment due to fail from stress.		
Avoid convexly uneven boards.		
Convex board is subject to substrate cracking or debasement of h	neat release.	
• It is recommended to apply adhesive or adhesive sheet with high	thermal conductivity	
for radiation of heat effectively.		
• Please take care about the influence of color change of adhesive		ng tern
period, which may affect light output or color due to change of r	effectance from backside.	

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• Do not touch resin part including white resin part on the surface of LEI No light emission may occur due to damage of resin or cutting wire of When using tweezers, please handle by ceramic substrate part and avoid For mounting, please handle by side part of ceramic or the specified are	LEDs by outer force. d touching resin part.	
Handling area		
5 Connecting method		
In case of solder connecting method, follow the conditions mentioned belo	OW.	
• Use Soldering iron with thermo controller (tip temperature 380 $^{\circ}$ C), with	hin 5 seconds per one place	
• Secure the solderwettability on whole solder pad and leads.		
• During the soldering process, put the ceramic board on materials whose	conductivity is poor enough	l
not to radiate heat of soldering.	ra caldaring	
• Warm up (with using a heated plate) the substrate is recommended before (preheat condition: 100 °C $\sim$ 150 °C, within 60 sec )	të soldernig.	
• Avoid touching a part of resin with soldering iron.		
• This product is not designed for reflow and flow soldering.		
• Avoid such lead arrangement as applying stress to solder-applied area.		
Please do not detach solder and make re-solder.		
Please solder evenly on each electrodes.		
Please prevent flux from touching to resin.		
6 Static electricity		
This product is subject to static electricity, so take measures to cope with i	it.	
Install circuit protection device to drive circuit, if necessary.		
⑦ Drive method		
• Any reverse voltage cannot be applied to LEDs when they are in operati	on or not.	
Design a circuit so that any flow of reverse or forward voltage can not be		
when they are out of operation.		
<ul> <li>Module is composed of LEDs connected in both series and parallel.</li> <li>Constant voltage power supply runs off more than specified current amount</li> </ul>	int due to lowered V $_{\rm F}$	
caused by temperature rise.		
Constant current power supply is recommended to drive.		
⑧ Cleaning		
Avoid cleaning, since silicone resin is eroded by cleaning.		
④ Color-tone variation		
Chromaticity of this product is monitored by integrating sphere right after	the operation.	
Chromaticity varies depending on measuring method, light spread condition	-	
Please verify your actual conditions before use.		

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(10) Safety			

- 10 Safety
  - ·Looking directly at LEDs for a long time may result in hurt your eyes.
  - •In case that excess current (over ratings) are supplied to the device, hazardous phenomena including abnormal heat generation, emitting smoke, or catching fire can be caused.
  - Take appropriate measures to excess current and voltage.
  - In case of solder connecting method, there is a possibility of fatigue failure by heat.
  - Please fix the leads in such case to protect from short circuit or leakage of electricity caused by contact.
  - Please confirm the safety standards or regulations of application devices.
  - •Please careful not to injure your hand by edge of ceramic substrate.
- ① Other cautions

Guarantee covers the compliance to the quality standards mentioned in the Specifications, however it does not cover the compatibility with application of the end-use, including assembly and usage environment.

In case any quality problems occurred in the application of end-use, details will be separately discussed and determined between the parties hereto.